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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

Jan I. Strandberg
Richard Scott Trevino
Thomas B. Blount

S-24-03

2. Name and address of receiving party(ies)

Name: Kulicke & Soffa Investments, Inc.

Internal Address:

Street Address: 2751 Centerville Road
Little Falls Center II

City: Wilmington State: DE ZIP: 19808

Additional name(s) of conveying party(ies) attached? Yes No.

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other:

Additional name(s) and address(es) attached? Yes No

Execution Dates: March 10, 2003; March 12, 2003; May 7, 2003

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s): 10/360,845

B. Patent No(s):

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William L. Shaffer
TOWNSEND AND TOWNSEND AND CREW LLP
Two Embarcadero Center, 8th Floor
San Francisco, California 94111-3834
(650) 326-2400

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41): -----\$40.00

- Enclosed
- Authorized to be charged to deposit account

06/02/2003 TDIAZ1 00000053 201430 10360845

01 FC:8021 40.00 CH

8. Deposit account number: 20-1430

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William L. Shaffer
Name of Person Signing
Atty. Reg. No. 37,234

Signature

5/22/03
Date

Total number of pages including cover sheet, attachments and document 4

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
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P.O. Box 1450
Alexandria, VA 22313-1450

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Jan I. Strandberg of 1405 Cedarmeadow Court, San Jose, CA 95131; Richard Scott Trevino of 2540 Marsha Way, San Jose, CA 95125; Thomas B. Blount of 6075 Marla Court, San Jose, CA 95124 hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: A HIGH DENSITY CHIP LEVEL PACKAGE FOR THE
 PACKAGING OF INTEGRATED CIRCUITS AND
 METHOD TO MANUFACTURE SAME

Date(s) of execution of Declaration: _____

Filing Date: February 6, 2003

Application No.: 10/360,845; and

WHEREAS, Kulicke & Soffa Investments, Inc., a corporation of the state of Delaware, located at 2751 Centerville Road, Little Falls Center II, Wilmington, DE 19808, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, 8th Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 3/10/03



JAN I. STRANDBERG

Dated: _____

RICHARD SCOTT TREVINO

Dated: _____

THOMAS B. BLOUNT

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Jan I. Strandberg of 1405 Cedarmeadow Court, San Jose, CA 95131; Richard Scott Trevino of 2540 Marsha Way, San Jose, CA 95125; Thomas B. Blount of 6075 Marla Court, San Jose, CA 95124 hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

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For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

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IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: _____

JAN I. STRANDBERG

Dated: 5/2/03



RICHARD SCOTT TREVINO

Dated: _____

THOMAS B. BLOUNT

